

PCN Number:	20180413001	PCN Date:	April 16, 2018
Title:	Datasheet for HDC2010		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



HDC2010

SNAS693A –JULY 2017–REVISED MARCH 2018

Changes from Original (July 2017) to Revision A	Page
• Changed <i>Features</i> bullet from: Automatic Sampling Rate to: Programmable Sampling Rate.....	1
• Changed <i>Features</i> bullet from: On Demand to: Trigger On Demand	1
• Changed <i>Heater</i> section	8
• Changed <i>Interrupt Description</i> section	9
• Changed HL_MASK to HL_ENABLE in <i>Humidity Low</i>	13
• Changed <i>Read Single Byte</i> header columns from: Slave address (W) to: Slave address (R)	16
• Changed <i>Read Multi Byte</i> header columns from: Slave address (W) to: Slave address (R).....	16
• Changed Address 0x0A reset value from: 11111111 to: 00000000	16
• Changed Address 0x0B reset value from: 0 to: 11111111	16
• Changed Address 0x0C reset value from: 11111111 to: 00000000	16
• Changed Address 0x0D reset value from: 0 to: 11111111	16
• Changed Address 0x04 bit 6 field description from: HH_STATUS to: TH_STATUS	18
• Changed Address 0x04 bit 5 field description from: HL_STATUS to: TL_STATUS	18
• Changed Address 0x04 bit 4 field description from: TH_STATUS to: HH_STATUS	18
• Changed Address 0x04 bit 3 field description from: TL_STATUS to: HL_STATUS	18
• Changed Address 0x07 field names for bits 7 through 3 from: _MASK to: _ENABLE	20
• Changed Address 0x07 field descriptions for bits 7 through 3 from: Interrupt mask to: Interrupt enable.....	20
• Changed Address 0x07 0 and 1 defaults from: enable and disable to: disable and enable.....	20
• Switched Register Address 0x0A HIGH and Register Address 0x0B LOW to Address 0x0A LOW and Address 0x0B HIGH.....	21
• Switched Register Address 0x0C HIGH and Register Address 0x0D LOW to Address 0x0C LOW and Address 0x0D HIGH.....	22
• Changed MEAS_TRIG bit description from: self-cleaning to: self-clearing	23

The datasheet number will be changing.

Device Family	Change From:	Change To:
HDC2010	SNAS693	SNAS693A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/HDC2010>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
HDC2010YPAT	HDC2010YPAR		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com